

PATENT

IN THE UNITED STATES PATENT OFFICE

Serial No.: ~~unassigned~~ 09/831763
Filed: ~~Herewith~~ 5-11-01
For: METHOD OF ELECTROLYTICALLY FORMING CONDUCTOR
STRUCTURES FROM HIGHLY PURE COPPER WHEN PRODUCING
INTEGRATED CIRCUITS
Inventor: Heinrich Meyer, Andreas Thies

Atty Doc. No.: 71-01

1791
HICKS

SAH
#3A
9.2601

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Please amend the above-identified application as follows:

In the Claims:

Claim 5, lines 1, change "4" to --3--;

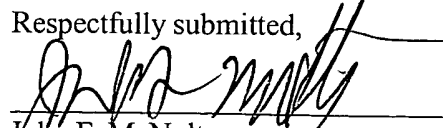
Claims 6, 7, and 9, line 1 of each, after "claims" insert --1-3--;

Replacement pages 22-23 reflecting the above changes are provided herewith.

REMARKS

The above amendments are made in order to eliminate multiple dependent claims that would otherwise be improperly dependent upon other multiple dependent claims and to place the claims in proper U.S. form.

Respectfully submitted,


John F. McNulty

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